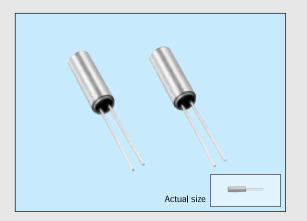
SMALL CYLINDER LOW/MEDIUM-FREQUENCY CRYSTAL UNIT

C-4-TYPE

- Photolithography finished allows uniform and stable performance.
- Small and light weight. (ø1.5 x 6mm)
- Excellent shock resistance and environmental capability.
- Most suitable for pagers and card products like PCMCIA.



Symbol Item Specifications Remarks 32.000 kHz to 120.000 kHz f Nominal frequency Please refer to frequency list below 192 kHz Storage temperature Tstg -20°C to +70°C Temperature Operating temperature range TOPR -10°C to +60°C Maximum drive level GL 1.0µW max. Recommended drive level (characteristics) DL 0.1µW typ. Soldering condition TSOL Under 280°C with in 5 sec. Do not heat the package at more than 150°C Frequency tolerance (standard) $\Delta f/f$ ±50ppm,±100ppm Ta=25°C, DL=0.1µW $25^{\circ}C \pm 5^{\circ}C$ θΤ Peak temperature (frequency) -0.04ppm/°C² max. Temperature coefficient (frequency) а 6pF to ∞ $C \vdash$ Load capacitance Please specify 32 kHz \leq f < 40 kHz: 55 k Ω max. 40 kHz \leq f < 60 kHz: 30 k Ω max. $60 \text{ kHz} \leq f < 70 \text{ kHz}: \ 25 \text{ k}\Omega \text{ max}.$ Series resistance Rı 70 kHz \leq f \leq 100 kHz: 22 k Ω max. 100 kHz < f \leq 120 kHz: 15 k Ω max. 192 kHz: 10 kΩ max. 3.0fF max. C1 Motional capacitance 1.5pF max. Shunt capacitance C_0 500 M Ω min. Insulation resistance IR ±5ppm/year max. fa Ta=25°C±3°C, first year Aging Three drops on a hard board from 75 cm or excitation ±5ppm max. Shock resistance S.R. test with 3000G x 0.3ms x 1/2 sine wave x 3 directions

Specifications (characteristics)

Frequency example

Туре	Frequency	C∟ Value
	26.6667 kHz	10.0pF, 11.0pF
	32.5600 kHz	7.0pF
	36.8640 kHz	13.5pF
	38.4000 kHz	10.0pF
	44,7340 kHz	10.0pF
C-2-TYPE	48.0000 kHz	15.0pF
	75.0000 kHz	6.5pF, 9.0pF,20.0pF
	77.5030 kHz	10.0pF, 20.0pF
	76.8000 kHz	6.0pF, 10.0pF, 11.0pF
	96.0000 kHz	6.0pF, 8.4pF,11.0pF
	153.6000 kHz	11.0pF
	307.2000 kHz	11.0pF
	38.4000 kHz	11.0pF
C-4-TYPE	50.0000 kHz	9.0pF
5 TE	76.8000 kHz	11.0pF
	77.5030 kHz	10.0pF
	192.0000 kHz	11.0pF

External dimensions (Unit: mm)



nin. ø2.0 max. ø0.2 nin. ø3.1 max. ø0.3 nin. ø2.0 max. ø0.2	1.1
nin. ø2.0 max. ø0.2	0.7
	0.7
nin. ø1.5 max. ø0.2	0.5
nin. ø1.2 max. ø0.1	5 0.3
	0.5
	nin. Ø1.5 max. Ø0.2

THE CRYSTALMASTER

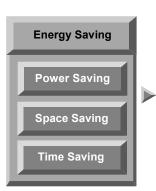


EPSON offers effective savings to its customers through a wide range of electronic devices, such as semiconductors, liquid crystal display (LCD) modules, and crystal devices. These savings are achieved through a sophisticated melding of three different efficiency technologies.

Power saving technology provides low power consumption at low voltages.

Space saving technology provides further reductions in product size and weight through super-precise processing and high-density assembly technology.

Time saving technology shortens the time required for design and development on the customer side and shortens delivery times.



Our concept of Energy Saving technology conserves resources by blending the essence of these three efficiency technologies. The essence of these technologies is represented in each of the products that we provide to our customers.

In the industrial sector, leading priorities include measures to counter the greenhouse effect by reducing CO2,

Resource Saving

measures to preserve the global environment, and the development of energyefficient products. Environmental problems are of global concern, and although the contribution of energysaving technology developed by EPSON may appear insignificant, we seek to contribute to the development of energy-saving products by our

customers through the utilization of our electronic devices. EPSON is committed to the conservation of energy, both for the sake of people and of the planet on which we live.





SEIKO EPSON CORP. QUARTZ DEVICE DIVISION acquired ISO9001 and ISO14001 certification by B.V.Q.I. (Bureau Veritas Quality International).

ISO9001 in October, 1992.

ISO14001 in November, 1997.

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